

SOT1762-2

SSOP32; plastic, shrink small outline package; 32 terminals; 0.65 mm pitch;
11 mm x 7.5 mm x 2.3 mm body

8 May 2023

Package information



1 Package summary

Terminal position code	D (double)
Package type descriptive code	SSOP32
Package type industry code	SSOP32
Package style descriptive code	SSOP (shrink small outline package)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	07-04-2023
Manufacturer package code	98ASA00259D

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	-	7.5	-	mm
package width	-	11	-	mm
seated height	-	2.3	2.45	mm
nominal pitch	-	0.65	-	mm
actual quantity of termination	-	32	-	



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2 Package outline

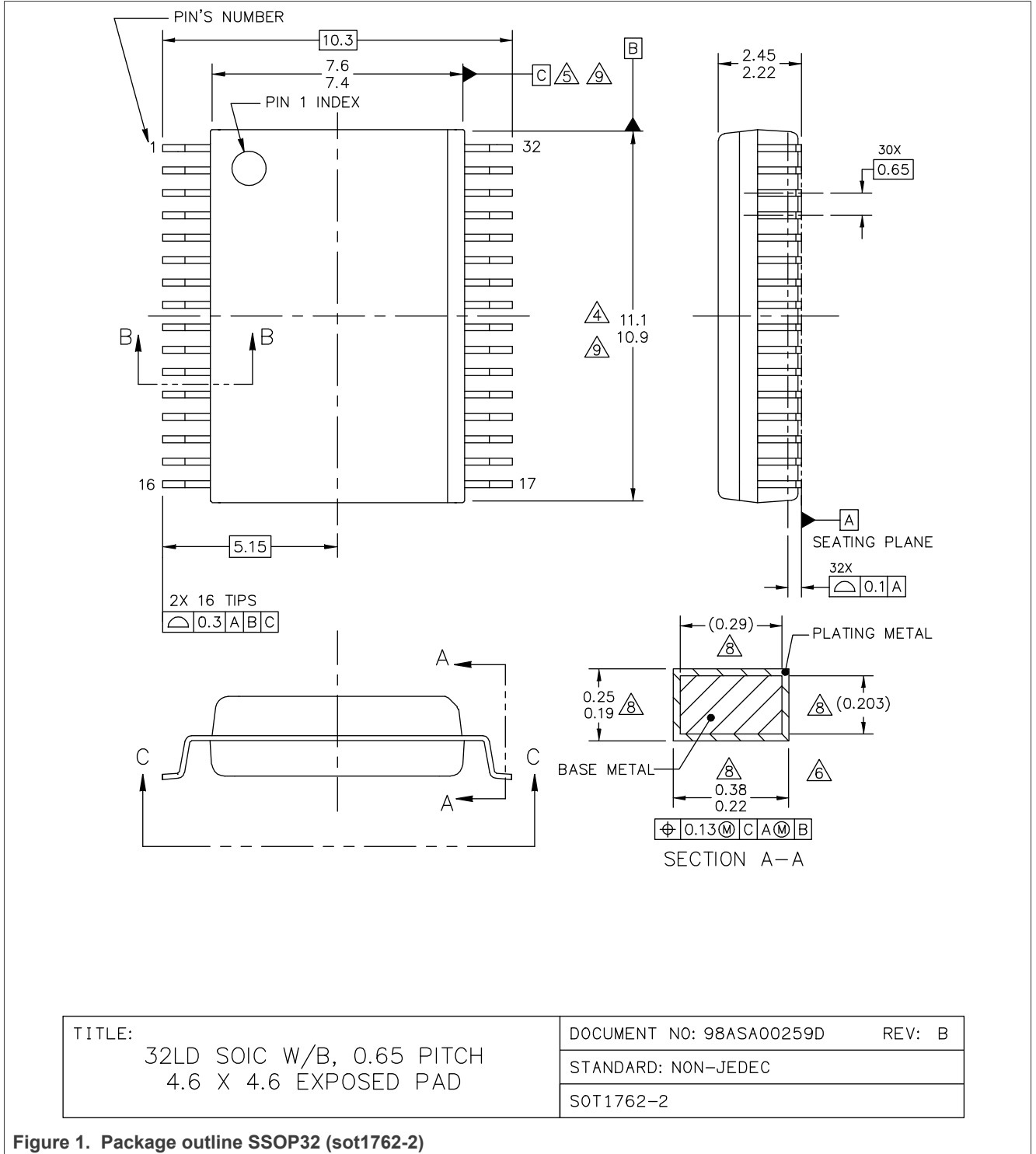


Figure 1. Package outline SSOP32 (sot1762-2)

SSOP32; plastic, shrink small outline package; 32 terminals; 0.65 mm pitch; 11 mm x 7.5 mm x 2.3 mm body

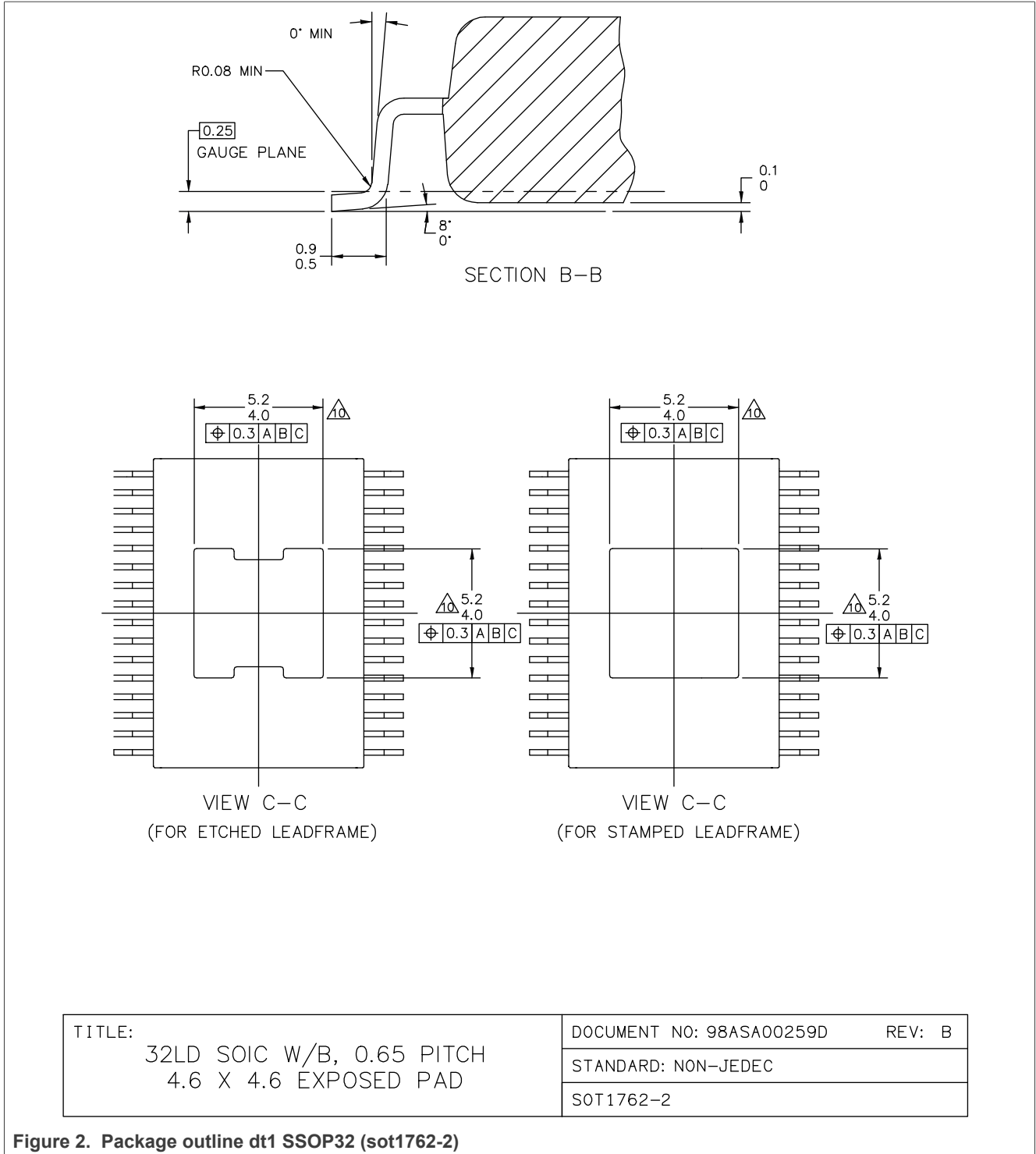


Figure 2. Package outline dt1 SSOP32 (sot1762-2)

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NOTES:

1. DIMENSIONS ARE IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. DATUMS B AND C TO BE DETERMINED AT THE PLANE WHERE THE BOTTOM OF THE LEADS EXIT THE PLASTIC BODY.
4. THIS DIMENSION DOES NOT INCLUDE MOLD FLASH, PROTRUSION OR GATE BURRS. MOLD FLASH, PROTRUSION OR GATE BURRS SHALL NOT EXCEED 0.15 mm PER SIDE. THIS DIMENSION IS DETERMINED AT THE PLANE WHERE THE BOTTOM OF THE LEADS EXIT THE PLASTIC BODY.
5. THIS DIMENSION DOES NOT INCLUDE INTER-LEAD FLASH OR PROTRUSIONS. INTER-LEAD FLASH AND PROTRUSIONS SHALL NOT EXCEED 0.25 mm PER SIDE. THIS DIMENSION IS DETERMINED AT THE PLANE WHERE THE BOTTOM OF THE LEADS EXIT THE PLASTIC BODY.
6. THIS DIMENSION DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL NOT CAUSE THE LEAD WIDTH TO EXCEED 0.4 mm. DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OR THE FOOT. MINIMUM SPACE BETWEEN PROTRUSION AND ADJACENT LEAD SHALL NOT LESS THAN 0.07 mm.
7. EXACT SHAPE OF EACH CORNER IS OPTIONAL.
8. THESE DIMENSIONS APPLY TO THE FLAT SECTION OF THE LEAD BETWEEN 0.10 mm AND 0.3 mm FROM THE LEAD TIP.
9. THE PACKAGE TOP MAY BE SMALLER THAN THE PACKAGE BOTTOM. THIS DIMENSION IS DETERMINED AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY EXCLUSIVE OF MOLD FLASH, TIE BAR BURRS, GATE BURRS AND INTER-LEAD FLASH, BUT INCLUDING ANY MISMATCH BETWEEN THE TOP AND BOTTOM OF THE PLASTIC BODY.
10. THESE DIMENSION RANGES DEFINE THE PRIMARY PCB KEEP-OUT AREA. MOLD LOCKING FEATURES MAY BE EXTENDED 0.7MM FROM MAXIMUM EXPOSED PAD SIZE.

TITLE: 32LD SOIC W/B, 0.65 PITCH 4.6 X 4.6 EXPOSED PAD	DOCUMENT NO: 98ASA00259D	REV: B
	STANDARD: NON-JEDEC	
	SOT1762-2	

Figure 3. Package outline note SSOP32 (sot1762-2)

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3 Legal information

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